## **DESCRIPTION**

The AM3415A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as1.8V. This device is suitable for use as a load switch or in PWM applications .It is ESD protested.

The AM3415A is available in SOT-23 package.

## ORDERING INFORMATION

Package Type	Part Number			
SOT-23	E3	AM3415AE3R		
501-23	E3	AM3415AE3VR		
Note	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				
Suffix "V" means Halogen free Package				

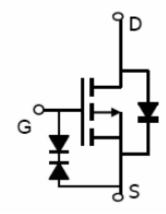
## **FEATURES**

- V<sub>DS</sub> = -20V,I<sub>D</sub> =-4A
  - $R_{DS(ON)} < 60 \text{m}\Omega @ V_{GS} = -2.5 \text{V}$
  - $R_{DS(ON)} < 47 m\Omega @ V_{GS} = -4.5 V$
  - ESD Rating: 2500V HBM
- High Power and current handing capability
- Lead free product is acquired
- Surface mount package
- Available in SOT-23 Package

### **APPLICATION**

- PWM application
- Load switch

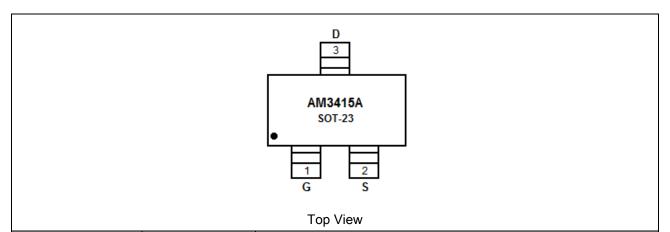
## TYPICAL APPLICATION



Schematic diagram

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# PIN DESCRIPTION



Pin#	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain

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P-CHANNEL ENHANCEMENT MODE POWER MOSFET

## ABSOLUTE MAXIMUM RATINGS

#### T<sub>A</sub>=25°Cunless otherwise noted

V <sub>DS</sub> , Drain-Source Voltage	-20V
V <sub>GS</sub> , Gate-Source Voltage	±10V
I <sub>D</sub> , Drain Current-Continuous	-4A
I <sub>DM</sub> , Drain Current-Pulsed NOTE1	-30A
P <sub>D</sub> , Maximum Power Dissipation	1.4W
T <sub>J</sub> ,T <sub>STG</sub> , Operating Junction and Storage Temperature Range	-55°C ~ 150°C

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Repetitive Rating: Pulse width limited by maximum junction temperature.

## THERMAL CHARACTERISTIC

Parameter	Symbol	MIN	MAX	Units
Thermal Resistance, Junction-to-Ambient NOTE2	R <sub>0JA</sub>		89.3	°C/W

NOTE2: Surface Mounted on FR4 Board, t ≤ 10 sec.

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## **ELECTRICAL CHARACTERISTICS**

T<sub>A</sub>=25°C, unless otherwise noted

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Off Characteristics				, ,,		
Drain-Source Breakdown	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20	_	-	V
Zero Gate Voltage Drain	$I_{DSS}$	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±10V,V <sub>DS</sub> =0V	-	-	±10	μΑ
On Characteristics NOTE3						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-0.4	-0.65	-1.0	V
Drain-Source On-State	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	34.	47	m()
Resistance	NDS(ON)	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-4A	-	44	60	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-4A	8	-	-	S
Dynamic Characteristics NOTE4						
Input Capacitance	$C_{lss}$	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V,	-	950	-	PF
Output Capacitance	Coss	, , , , ,	_	165	-	
Reverse Transfer Capacitance	$C_{rss}$	F=1.0MHz	-	120	-	
Switching Characteristics NOTE4						
Turn-on Delay Time	t <sub>D(ON)</sub>		-	12	-	
Turn-on Rise Time	<b>t</b> R	$V_{DD}$ =-10V, R <sub>L</sub> =2. 5 $\Omega$	-	10	-	nS
Turn-Off Delay Time	t <sub>D(OFF)</sub>	$V_{GS}$ =-4.5 $V$ , $R_{GEN}$ =3 $\Omega$	-	19	-	113
Turn-Off Fall Time	t⊧		-	25	-	
Total Gate Charge	$Q_{\mathrm{G}}$	V <sub>DS</sub> =-10V,I <sub>D</sub> =-4A,	_	12	-	nC
Gate-Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> =-10V,I <sub>D</sub> =-4A, V <sub>GS</sub> =-4.5V	_	1.4	-	
Gate-Drain Charge	$Q_{GD}$		-	3.6	-	
Drain-Source Diode						
Diode Forward Voltage NOTE3	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-1A	-	-	-1.2	V
Diode Forward Current NOTE2	ls		-	-	-2.2	Α

NOTE2: Surface Mounted on FR4 Board, t ≤ 10 sec.

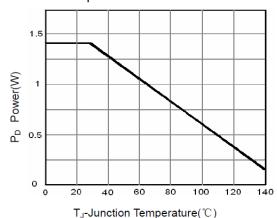
NOTE3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

NOTE4: Guaranteed by design, not subject to production

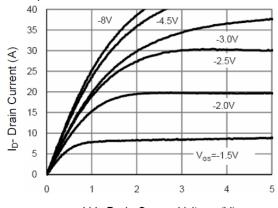
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## TYPICAL PERFORMANCE CHARACTERISTICS

#### 1. Power Dissipation

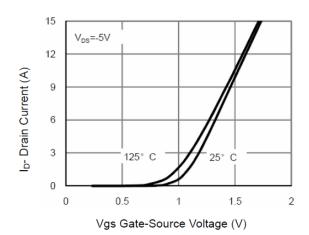


3. Output CHARACTERISTICS

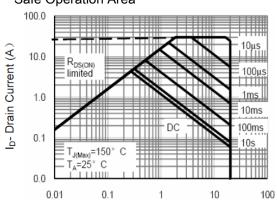


Vds Drain-Source Voltage (V)

#### 5. Transfer Characteristics

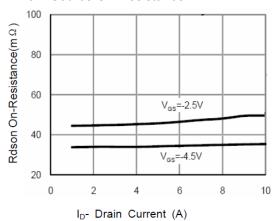


### 2. Safe Operation Area

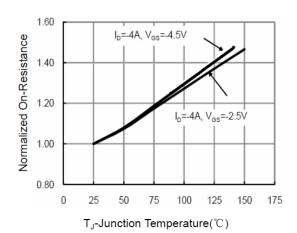


Vds Drain-Source Voltage (V)

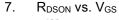
### 4. Drain-Source On-Resistance

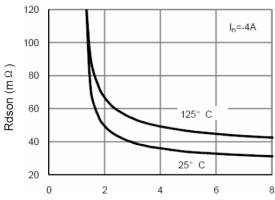


6. Drain-Source On-Resistance



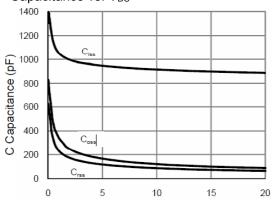
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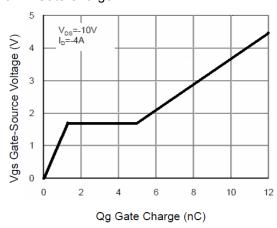
Vgs Gate-Source Voltage (V)

### 8. Capacitance vs. V<sub>DS</sub>

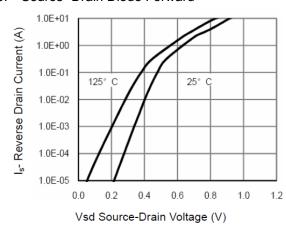


Vds Drain-Source Voltage (V)

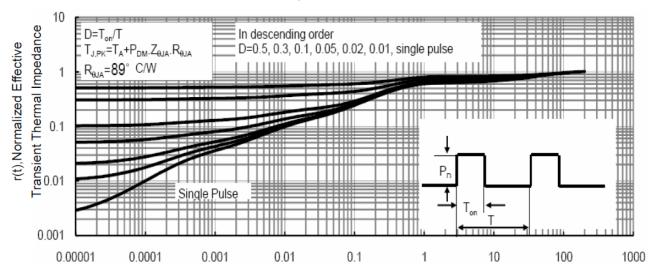
#### 9. Gate Charge



## 10. Source- Drain Diode Forward

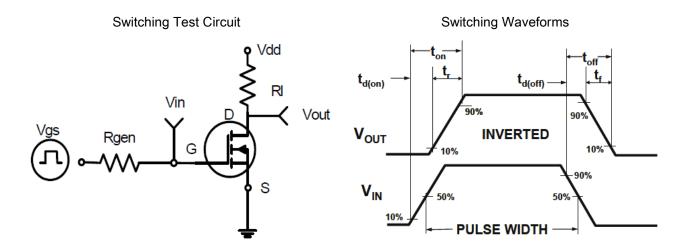


#### 11. Normalized Maximum Transient Thermal Impedance



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## **DETAILED INFORMATION**

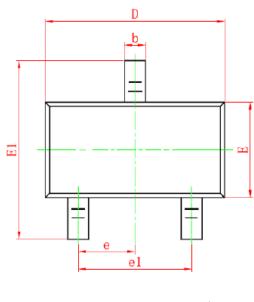


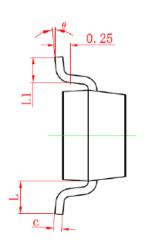
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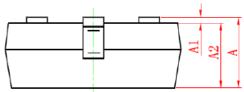


## PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)







SYMBOL	MIN	MAX	
Α	0.900	1.150	
A1	0.000	0.100	
A2	0.900	1.050	
b	0.300	0.500	
С	0.080	0.150	
D	2.800	3.000	
Е	1.200	1.400	
E1	2.250	2.550	
е	0.950(BSC)		
e1	1.800	2.000	
L	0.300	0.500	
θ	0°	8°	

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